

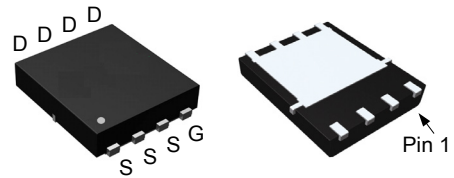
### Features

- 30V/80A  
 $R_{DS(ON)}=3.7m\Omega(\text{typ.})@V_{GS}=10V$   
 $R_{DS(ON)}=5m\Omega(\text{typ.})@V_{GS}=4.5V$
- 100% UIS +  $R_g$  Tested
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)

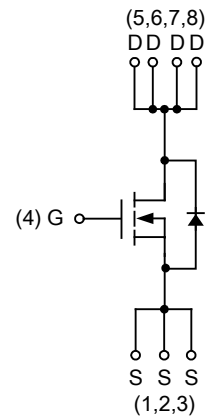
### Applications

- Power Management in Notebook Computer, Portable Equipment and Battery Powered Systems.
- Adapter of NB.

### Pin Description



DFN5x6A-8\_EP



N-Channel MOSFET

### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
XPX3080RD	PDFN5*6-8L	3080RD XXX YYYY	5000

**Absolute Maximum Ratings** ( $T_A=25^\circ\text{C}$  Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit	
<b>Common Ratings</b>				
$V_{DSS}$	Drain-Source Voltage	30	V	
$V_{GSS}$	Gate-Source Voltage	$\pm 20$		
$T_J$	Maximum Junction Temperature	-55 to 150	$^\circ\text{C}$	
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$	
$I_S$	Diode Continuous Forward Current	$T_C=25^\circ\text{C}$	18	A
$I_D$	Continuous Drain Current	$T_C=25^\circ\text{C}$	80 <sup>a</sup>	A
		$T_C=100^\circ\text{C}$	45	
$I_{DM}^b$	Pulse Drain Current	$T_C=25^\circ\text{C}$	240	A
$P_D$	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	39	W
		$T_C=100^\circ\text{C}$	16	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	Steady State	3.2	$^\circ\text{C/W}$
$I_D$	Continuous Drain Current	$T_A=25^\circ\text{C}$	16	A
		$T_A=70^\circ\text{C}$	12.7	
$I_{DM}^b$	Pulse Drain Current	$T_A=25^\circ\text{C}$	64	A
$P_D$	Maximum Power Dissipation	$T_A=25^\circ\text{C}$	1.92	W
		$T_A=70^\circ\text{C}$	1.23	
$R_{\theta JA}^c$	Thermal Resistance-Junction to Ambient	$t \leq 10\text{s}$	24	$^\circ\text{C/W}$
		Steady State	65	
$I_{AS}^d$	Avalanche Current, Single pulse	$L=0.1\text{mH}$	44	A
$E_{AS}^d$	Avalanche Energy, Single pulse	$L=0.1\text{mH}$	97	mJ

Note a : Max. continuous current is limited by bonding wire.

Note b : Pulse width is limited by max. junction temperature.

Note c : Surface mounted on 1in<sup>2</sup> pad area, steady state  $t = 999\text{s}$ .

Note d : UIS tested and pulse width limited by maximum junction temperature 150 $^\circ\text{C}$  (initial temperature  $T_J=25^\circ\text{C}$ ).

**N-Channel Enhancement Mode MOSFET**
**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

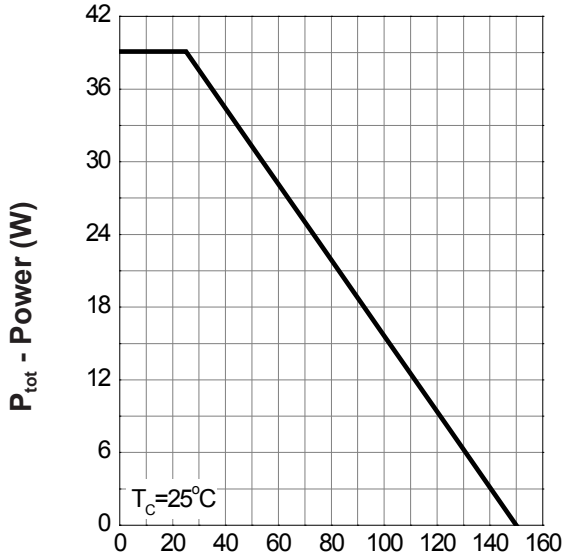
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu A$	30	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=24V, V_{GS}=0V$ $T_J=85^\circ\text{C}$	-	-	1	$\mu A$
			-	-	30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	1.3	1.7	2.2	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
$R_{DS(ON)}^e$	Drain-Source On-state Resistance	$V_{GS}=10V, I_{DS}=25A$	-	3.7	4.5	m $\Omega$
		$V_{GS}=4.5V, I_{DS}=20A$	-	5	6.5	
Gfs	Forward Transconductance	$V_{DS}=5V, I_{DS}=20A$	-	39	-	S
<b>Diode Characteristics</b>						
$V_{SD}^e$	Diode Forward Voltage	$I_{SD}=20A, V_{GS}=0V$	-	0.8	1.1	V
$t_{rr}$	Reverse Recovery Time	$I_{DS}=25A, dI_{SD}/dt=100A/\mu s$	-	21.2	-	ns
$t_a$	Charge Time		-	9.1	-	
$t_b$	Discharge Time		-	12.1	-	
$Q_{rr}$	Reverse Recovery Charge		-	6	-	
<b>Dynamic Characteristics<sup>f</sup></b>						
$R_G$	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	-	0.9	-	$\Omega$
$C_{iss}$	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=15V,$ Frequency=1.0MHz	-	2500	-	pF
$C_{oss}$	Output Capacitance		-	450	-	
$C_{riss}$	Reverse Transfer Capacitance		-	250	-	
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=15V, R_L=15\Omega,$ $I_{DS}=1A, V_{GEN}=10V,$ $R_G=6\Omega$	-	17.2	31	ns
$t_r$	Turn-on Rise Time		-	10.5	19	
$t_{d(OFF)}$	Turn-off Delay Time		-	51.4	93	
$t_f$	Turn-off Fall Time		-	16.6	30	
<b>Gate Charge Characteristics<sup>f</sup></b>						
$Q_g$	Total Gate Charge	$V_{DS}=15V, V_{GS}=10V,$ $I_{DS}=25A$	-	42.6	59.6	nC
$Q_g$	Total Gate Charge	$V_{DS}=15V, V_{GS}=4.5V,$ $I_{DS}=25A$	-	19.6	-	
$Q_{gth}$	Threshold Gate Charge		-	4.8	-	
$Q_{gs}$	Gate-Source Charge		-	8.4	-	
$Q_{gd}$	Gate-Drain Charge		-	4.8	-	

Note e : Pulse test ; pulse width $\leq 300\text{ms}$ , duty cycle $\leq 2\%$ .

Note f : Guaranteed by design, not subject to production testing.

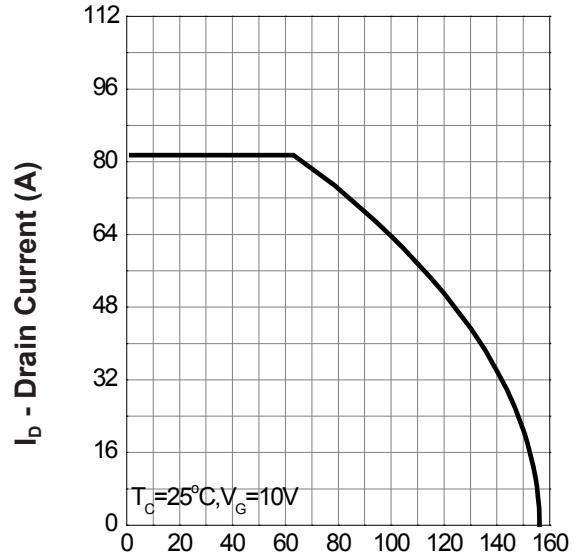
Typical Operating Characteristics

Power Dissipation



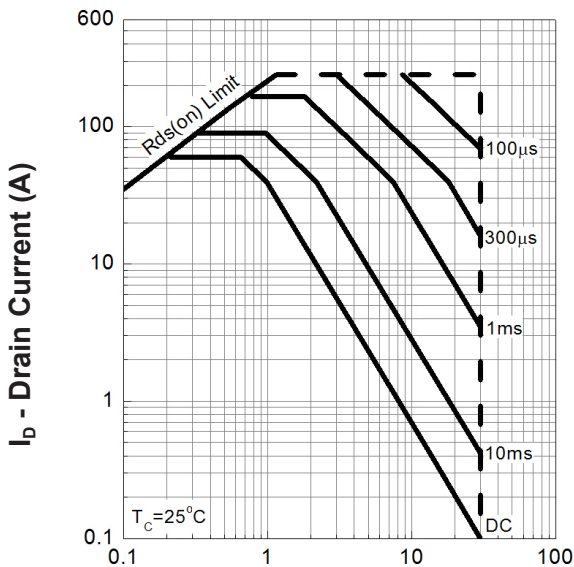
T<sub>j</sub> - Junction Temperature (°C)

Drain Current



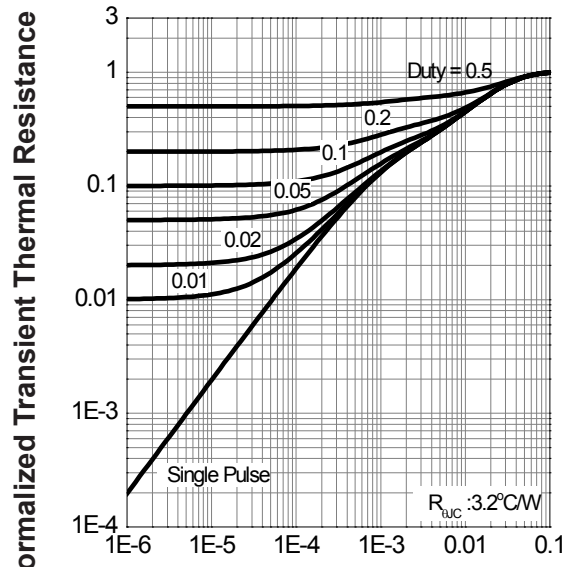
T<sub>j</sub> - Junction Temperature (°C)

Safe Operation Area



V<sub>DS</sub> - Drain - Source Voltage (V)

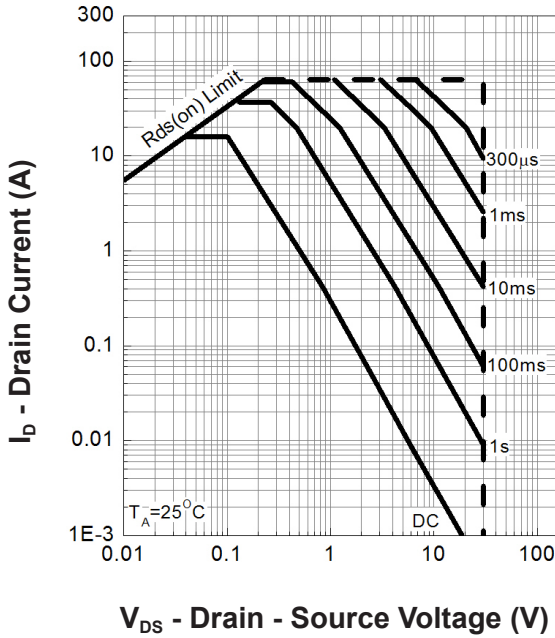
Thermal Transient Impedance



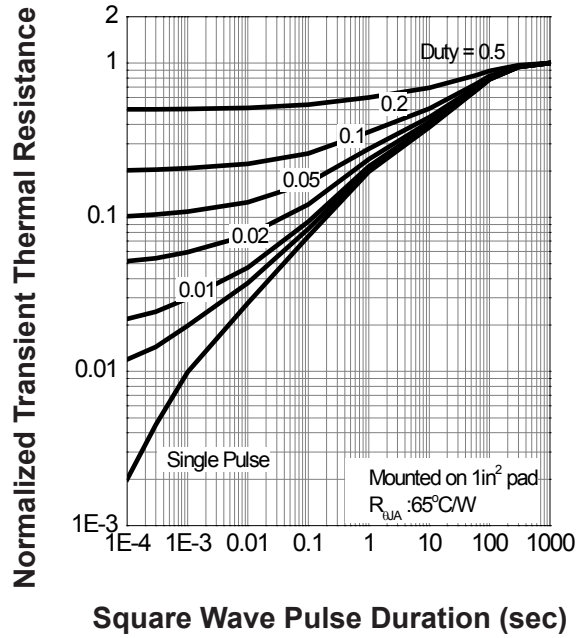
Square Wave Pulse Duration (sec)

Typical Operating Characteristics(Cont.)

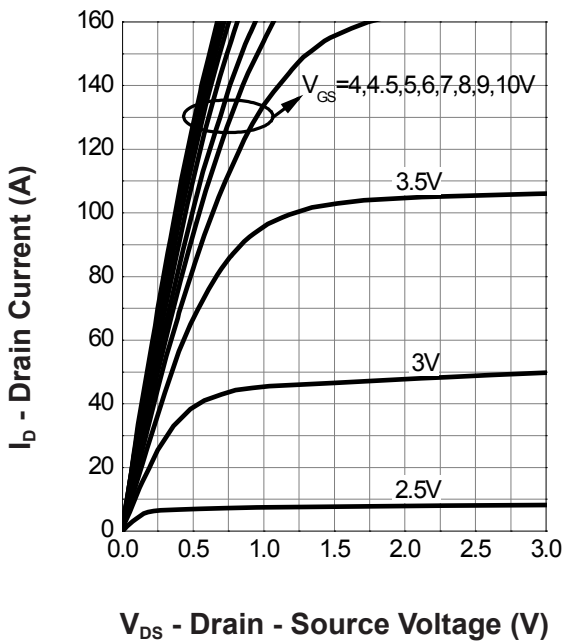
Safe Operation Area



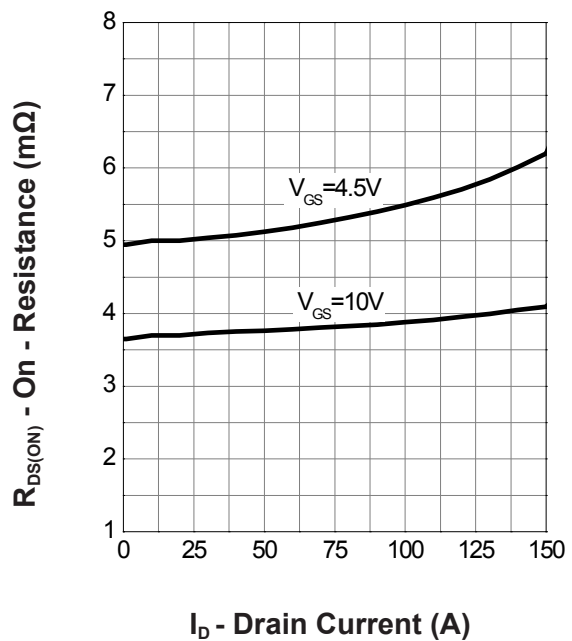
Thermal Transient Impedance



Output Characteristics

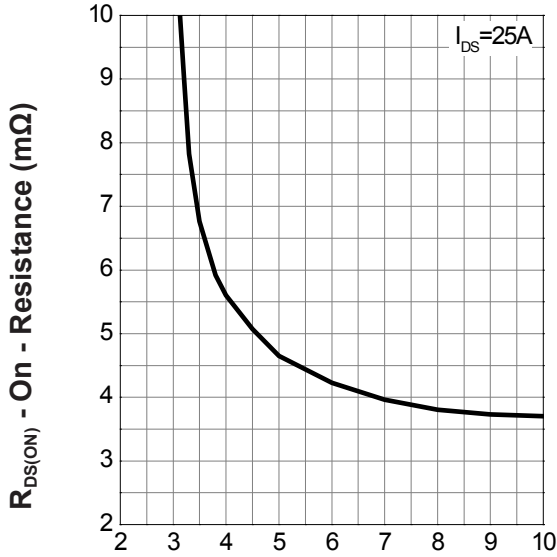


Drain-Source On Resistance



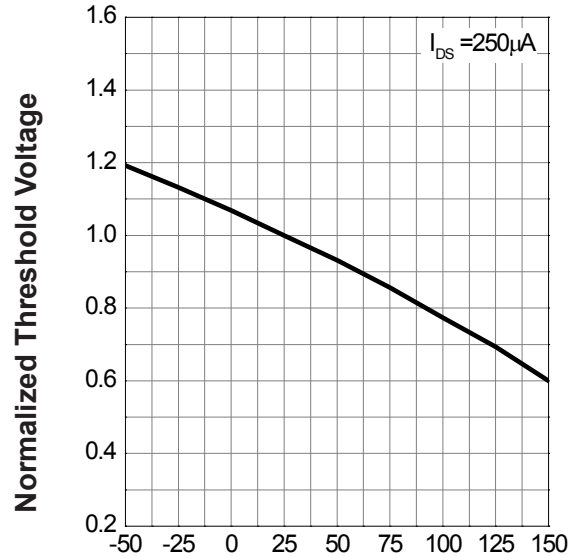
Typical Operating Characteristics(Cont.)

Gate-Source On Resistance



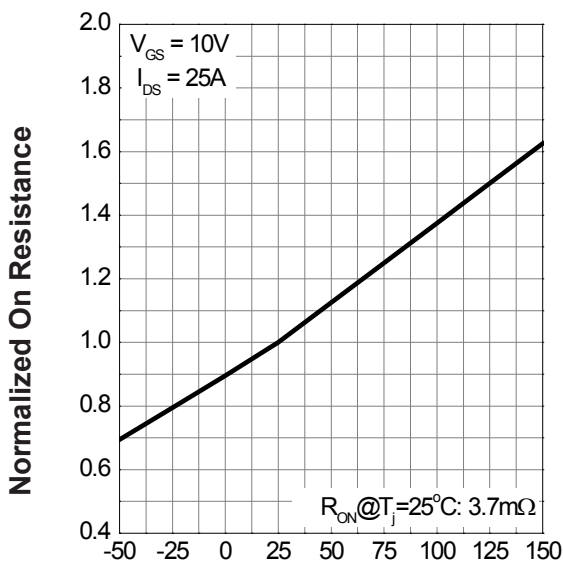
V<sub>GS</sub> - Gate - Source Voltage (V)

Gate Threshold Voltage



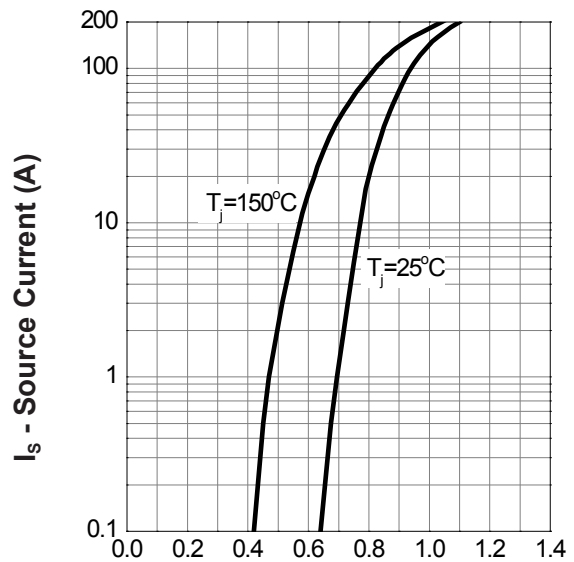
T<sub>J</sub> - Junction Temperature (°C)

Drain-Source On Resistance



T<sub>J</sub> - Junction Temperature (°C)

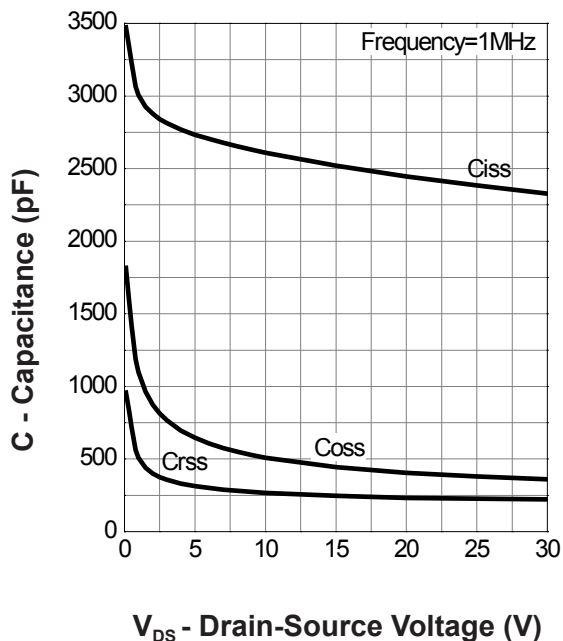
Source-Drain Diode Forward



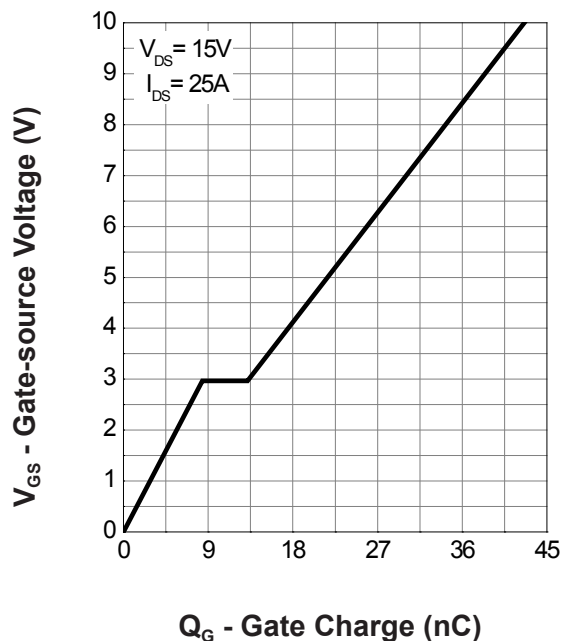
V<sub>SD</sub> - Source - Drain Voltage (V)

Typical Operating Characteristics(Cont.)

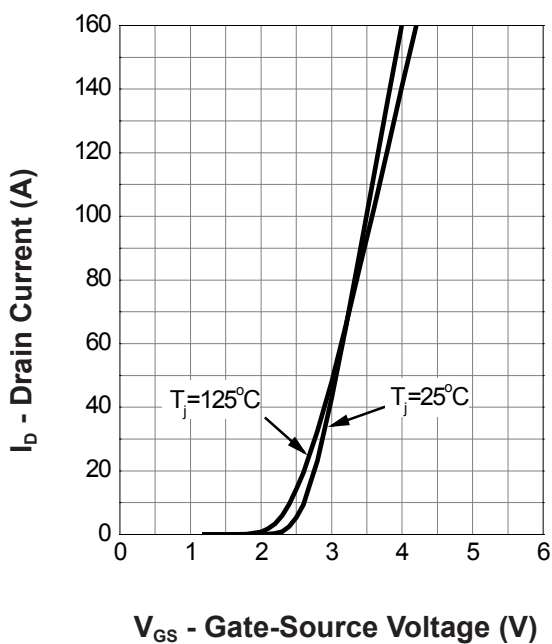
Capacitance



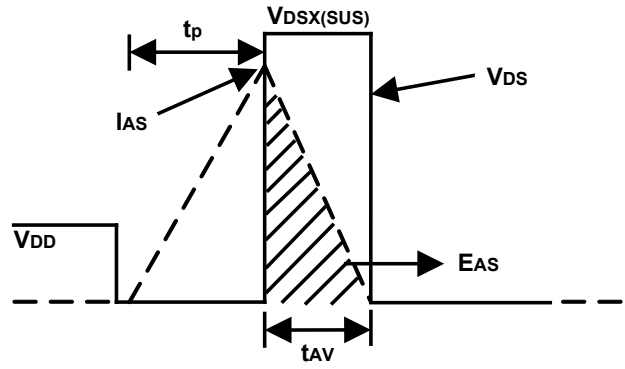
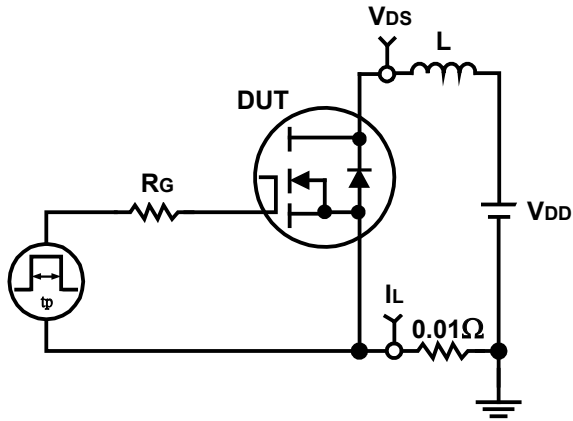
Gate Charge



Transfer Characteristics



### Avalanche Test Circuit and Waveforms



### Switching Time Test Circuit and Waveforms

